

<b>PATENT ASSIGNMENT COVER SHEET</b>
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EPAS ID: PAT5875653

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
HONG WAN NG	04/28/2014
SENG KIM YE	04/28/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	MICRON TECHNOLOGY, INC.
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<b>City:</b>	BOISE
<b>State/Country:</b>	IDAHO
<b>Postal Code:</b>	83707-0006
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16678195
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
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<b>Phone:</b>	206-359-8000
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<b>ATTORNEY DOCKET NUMBER:</b>	010829-9108.US02
<b>NAME OF SUBMITTER:</b>	CHRISTINE DUNN
<b>SIGNATURE:</b>	/Christine Dunn/
<b>DATE SIGNED:</b>	12/18/2019
<b>Total Attachments: 4</b>	
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### ASSIGNMENT BY INVENTORS

This Assignment is by the following individuals (the "Assignors"):

- Hong Wan Ng, having a mailing address of Block 75C, #24-76 Redhill Road, Singapore 153075, Singapore; and
- Seng Kim Ye, having a mailing address of Block 311C, #05-32 Anchorvale Lane, Singapore 543311, Singapore.

The Assignors invented one or more certain inventions (the "Invention(s)") described in an application for Letters Patent of the United States titled STACKED SEMICONDUCTOR DIE ASSEMBLIES WITH SUPPORT MEMBERS AND ASSOCIATED SYSTEMS AND METHODS, naming the Assignors as inventors, and filed on \_\_\_\_\_ as U.S. Application No. \_\_\_\_\_ (the "Application"). The Assignors authorize the Assignee, identified below, or its representatives to insert the application number and filing date of the Application when known.

Micron Technology, Inc., a corporation of Delaware having its principal place of business at 8000 S. Federal Way, P.O. Box 6, Boise, Idaho 83707-0006 ("Assignee"), desires to acquire the entire right, title and interest in and to the Invention(s) and the Application, and in and to any patents (collectively, "Patents") that may be granted for the Invention(s) in the United States or in any foreign countries.

For valuable consideration, the receipt and sufficiency of which Assignors acknowledge, Assignors hereby sell, assign, and transfer to Assignee, its successors, legal representatives and assigns, the entire right, title and interest in and to: the Invention(s), the Application, and any Patents; any divisions, continuations, and continuations-in-part of the Application and any other application claiming priority rights from the Application; any reissues, reexaminations, or extensions of any and all Patents; the right to file foreign applications directly in the name of Assignee; and the right to claim priority rights deriving from the Application (collectively, the "Rights"). Assignors warrant that Assignors own the Rights, and that the Rights are unencumbered. Assignors also agree to not sign any writing or do any act conflicting with this assignment, and, without further compensation, sign all documents and do




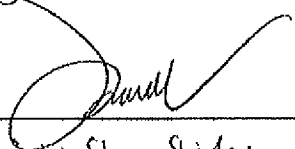
such additional acts as Assignee deems necessary or desirable to: perfect Assignee's enjoyment of the Rights; conduct proceedings regarding the Rights, including any litigation or interference proceedings; or perfect or defend title to the Rights. This Assignment may be executed in counterparts.



Date: 4/29/2014

  
\_\_\_\_\_  
Hong Wan Ng

Witness to Signature by Hong Wan Ng:


  
\_\_\_\_\_  
Signature Eng Yeow Chon  
\_\_\_\_\_  
Printed Name  
\_\_\_\_\_  
Signature   
\_\_\_\_\_  
Printed Name Tan Li Shan Shirkay  
\_\_\_\_\_

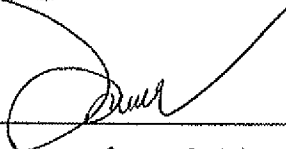


Date: 04/28/2014

  
\_\_\_\_\_  
Seng Kim Ye

Witness to Signature by Seng Kim Ye:

  
\_\_\_\_\_  
Signature Ong Yeaw Chon  
Printed Name

  
\_\_\_\_\_  
Signature Tan Li Shan Shirley  
Printed Name

